ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pan-America	ockburn, Illinois. A	ll rights reserved utions.	Inder both This d	ocument parts, the	t is a declaration er	on of the sub compasses	bstances all lower	within the manufactur r level materials for w	er listed i hich the 1	item. Note: i nanufacture	f the item is an as r has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type * http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information												
Company name*	pany name* Company unique ID			Unique ID Authority					Response Date*			
onsemi									2025-06-04			
Contact Name	Title - Contac		Ph	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*	thorized Representative* Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Complian				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr	Item Number	Mfr Item Name		E	ffective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type
NVN 1G	4FS9D6P04M8LT MV8 P-ch 40V SO		O-8FL Portfolio Expar	nsion 20	025-06-04	1		MY1		100.77	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base A	Ferminal Base Alloy J-S		g	Peak Proce	Process Body Temperature Max Time at Peal		e Max Time at Peak	Temperature Number of		per of Reflow Cyd	cles
Matte Tin (Sn) - annealed	Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30	seco	nds 3		
Comments												
level 1 - maximum time at peak temperature durin	g soldering is 10-3	0 seconds										
For more information regarding material composit	ion please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach Solder	2.33	mg	Supplier	Silver (Ag)	7440-22-4		0.0582	mg
			А	Lead (Pb)	7439-92-1	7a	2.1553	mg
			Supplier	Tin (Sn)	7440-31-5		0.1165	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	42.24	mg		Epoxy resin	proprietary data		3.168	mg
			Supplier	Phenolic Resin	Proprietary Data		1.056	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.168	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.6368	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg